



Approved  
CX 3/13/03  
PATENT

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Darius  
as  
1/16/03*

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Akram et al.

Serial No.: 09/241,177

Filed: February 1, 1999

For: HIGH DENSITY MODULARITY FOR  
IC'S

Confirmation No.: 8330

Examiner: C. Novacek

Group Art Unit: 2822

Attorney Docket No.: 3638US (98-0093)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

December 31, 2002

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RECEIVED  
JAN - 9 2003  
TC 2800 MAIL ROOM

TRANSMITTAL OF FORMAL DRAWINGS

Commissioner for Patents  
Washington, D.C. 20231

Sir:

Attached please find the formal drawings for this application.

Respectfully submitted,

*James R. Duzan*

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Date: December 31, 2002  
JRD/jml:djp

Enclosure: Formal Drawings (11 sheets, 15 figures)